

Multilayer Ceramic Chip Capacitors

CGA9P2X7R1E226M250KA



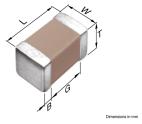






TDK item description CGA9P2X7R1E226MT****

Applications	Automotive Grade
Feature	General General (Up to 50V) AEC-Q200 AEC-Q200
Series	CGA9(5750) [EIA 2220]
Status	Production



Size		
Length(L)	5.70mm ±0.40mm	
Width(W)	5.00mm ±0.40mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	4.10mm to 4.80mm	
Recommended Land Pattern (PB)	1.20mm to 1.40mm	
Recommended Land Pattern (PC)	4.00mm to 5.00mm	

Electrical Characteristics		
Capacitance	22μF ±20%	
Rated Voltage	25VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	3%	
Insulation Resistance (Min.)	22ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	Yes	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	500pcs	

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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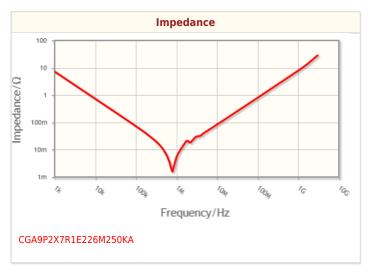


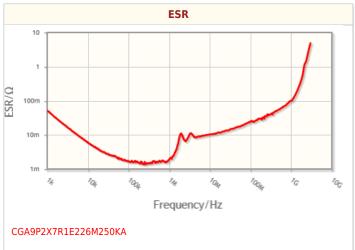


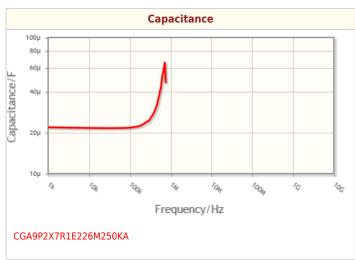




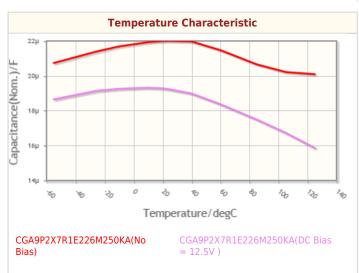
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

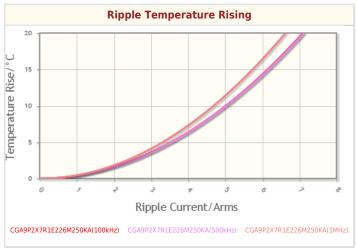












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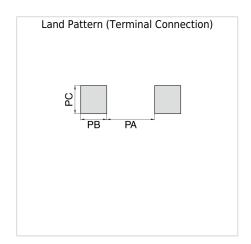








Associated Images



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